

ABSTRACT

A semiconductor chip 1 is provided with a first electrode 2 formed at a first corner of a crystal substrate 1a generally quadrangular as viewed in plan, and with a second electrode 3 formed to extend along two sides of the crystal substrate 1a, these sides including between them a second corner located diagonally away from the first corner. The first electrode 2 and the second electrode 3 are connected to a first lead 15 and second leads 16a, 16b formed on the circuit substrate 10 via solder paste 20. The narrow first lead 15 extends transversely to a side of the crystal substrate 1a, and the second leads 16a, 16b extends in the opposite direction to that of the first lead 15. The first lead 15 and the second lead 16b are offset from each other by an appropriate distance. With such arrangements, the surface tension of melted solder prevents the semiconductor chip 1 from being fixed to the circuit substrate 10 with a slanting posture.